

# UNISONIC TECHNOLOGIES CO., LTD

2NM80-Q **Power MOSFET** 

# 2.0A, 800V N-CHANNEL SUPER-JUNCTION MOSFET

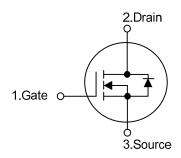
#### **DESCRIPTION**

The UTC 2NM80-Q is a Super Junction MOSFET Structure and is designed to have better characteristics, such as fast switching time, low gate charge, low on-state resistance and a high rugged avalanche characteristics. This power MOSFET is usually used at AC-DC converters for power applications.

#### **FEATURES**

- \*  $R_{DS(ON)} \le 3.8 \Omega$  @  $V_{GS}$ =10V,  $I_D$ =1.0A
- \* Fast switching capability
- \* Avalanche energy tested
- \* Improved dv/dt capability, high ruggedness

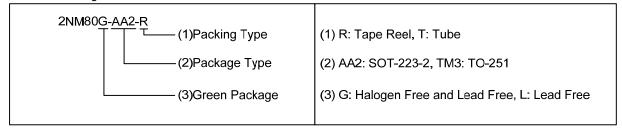
#### **SYMBOL**

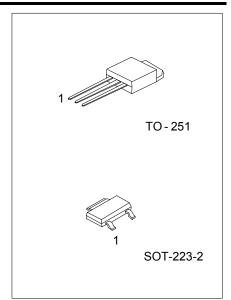


#### ORDERING INFORMATION

Ordering Number		Dealtage	Pin	Assignm	Daakina		
Lead Free	Halogen Free	Package	1	2	3	Packing	
2NM80L-AA2-R	2NM80G-AA2-R	SOT-223-2	G	D	S	Tape Reel	
2NM80L-TM3-T	2NM80G-TM3-T	TO-251	G	D	S	Tube	

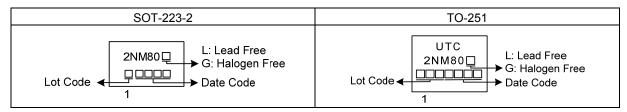
Note: Pin Assignment: G: Gate S: Source D: Drain





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### ■ MARKING



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### ■ ABSOLUTE MAXIMUM RATINGS (T<sub>C</sub> = 25°C, unless otherwise specified)

PARAMETER		SYMBOL	RATINGS	UNIT
Drain-Source Voltage		$V_{DSS}$	800	V
Gate-Source Voltage		$V_{GSS}$	±30	V
Continuous Drain Current	Continuous	I <sub>D</sub>	2	Α
Pulsed Drain Current	Pulsed (Note 2)	I <sub>DM</sub>	4	Α
Single Pulsed Avalanche Energy	Single Pulsed (Note 3)	E <sub>AS</sub>	50	mJ
Peak Diode Recovery dv/dt (Note 4)		dv/dt	3.69	V/ns
Power Dissipation	SOT-223-2	Б	1.5	W
	TO-251	$P_D$	12	W
Junction Temperature		TJ	+150	°C
Storage Temperature		T <sub>STG</sub>	-55 ~ +150	°C

Notes: 1. Absolute maximum ratings are those values beyond which the device could be permanently damaged. Absolute maximum ratings are stress ratings only and functional device operation is not implied.

- 2. Repetitive Rating: Pulse width limited by maximum junction temperature.
- 3. L = 100mH,  $I_{AS}$  = 1.0A,  $V_{DD}$  = 90V,  $R_{G}$  = 25 $\Omega$ , Starting  $T_{J}$  = 25 $^{\circ}$ C.
- 4.  $I_{SD} \le 2.0A$ , di/dt  $\le 200A/\mu s$ ,  $V_{DD} \le BV_{DSS}$ , Starting  $T_J = 25$ °C.

#### ■ THERMAL DATA

PARAMETER		SYMBOL	RATINGS	UNIT
Junction to Ambient	SOT-223-2	0	150	°C/W
	TO-251	θ <sub>JA</sub>	110	°C/W
lunation to Coop	SOT-223-2	0	83.3	°C/W
Junction to Case	TO-251	θις	10.4	°C/W

Note: Device mounted on FR-4 substrate P<sub>C</sub> board, 2oz copper, with 1inch square copper plate.

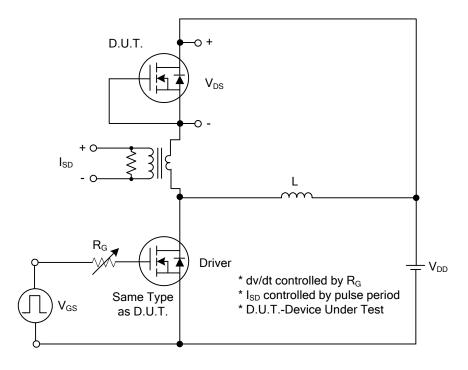
# ■ ELECTRICAL CHARACTERISTICS (T」=25°C, unless otherwise specified)

PARAMETER		SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNIT
OFF CHARACTERISTICS							
Drain-Source Breakdown Voltage		$BV_{DSS}$	$V_{GS}$ =0V, $I_D$ =250 $\mu$ A	800			V
Drain-Source Leakage Current		I <sub>DSS</sub>	V <sub>DS</sub> =800V, V <sub>GS</sub> =0V			10	μΑ
Gate-Source Leakage Current	Forward		$V_{GS}$ =30V, $V_{DS}$ =0V			100	nA
	Reverse		$V_{GS}$ =-30V, $V_{DS}$ =0V			-100	nA
ON CHARACTERISTICS							
Gate Threshold Voltage		$V_{GS(TH)}$	$V_{DS}=V_{GS}$ , $I_D=250\mu A$	2.5		4.5	V
Static Drain-Source On-State Re	esistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =1.0A			3.8	Ω
DYNAMIC CHARACTERISTICS	<b>3</b>						
Input Capacitance		C <sub>ISS</sub>			150		pF
Output Capacitance	Output Capacitance		$V_{GS}$ =0V, $V_{DS}$ =50V, f=1.0MHz		23		pF
Reverse Transfer Capacitance		C <sub>OSS</sub>			2.5		pF
SWITCHING CHARACTERISTIC	cs						
Total Gate Charge (Note 1)		$Q_G$	V <sub>DS</sub> =640V, V <sub>GS</sub> =10V, I <sub>D</sub> =2.0A (Note 1, 2)		13.5		nC
Gate to Source Charge		$Q_GS$			5.2		nC
Gate to Drain Charge		$Q_GD$	(Note 1, 2)		2.8		nC
Turn-ON Delay Time (Note 1)		$t_{D(ON)}$			4		nS
Rise Time		$t_R$	V <sub>DS</sub> =100V, V <sub>GS</sub> =10V,		17		nS
Turn-OFF Delay Time		$t_{D(OFF)}$	$I_D$ =2.0A, $R_G$ =25 $\Omega$ (Note 1, 2)		25		nS
Fall-Time		$t_{F}$			30		nS
<b>SOURCE- DRAIN DIODE RATIF</b>	NGS AND CHA	ARACTERIST	rics		ā.		
Maximum Continuous Drain-Source Diode		Is				2	Α
Forward Current							^
Maximum Pulsed Drain-Source Diode		I <sub>SM</sub>				4	Α
Forward Current							
Drain-Source Diode Forward Voltage (Note 1)		$V_{SD}$	I <sub>S</sub> =2.0A, V <sub>GS</sub> =0V			1.4	V
Body Diode Reverse Recovery Time (Note 1)		t <sub>rr</sub>	I <sub>S</sub> =2.0A, V <sub>GS</sub> =0V,		230		nS
Body Diode Reverse Recovery Charge		$Q_{rr}$	dI <sub>F</sub> /dt=100A/μs		1.1		μC

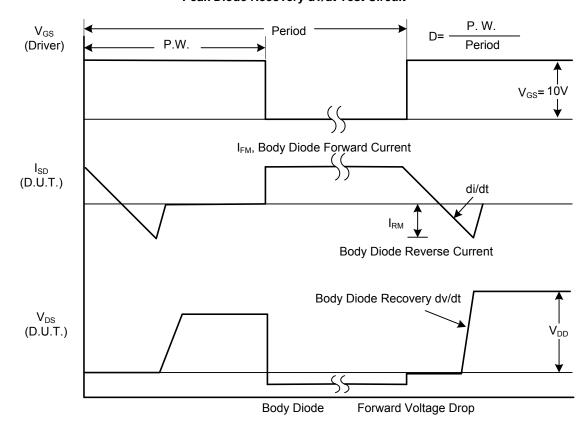
Notes: 1. Pulse Test : Pulse width ≤ 300µs, Duty cycle ≤ 2%.

<sup>2.</sup> Essentially independent of operating ambient temperature.

#### ■ TEST CIRCUITS AND WAVEFORMS



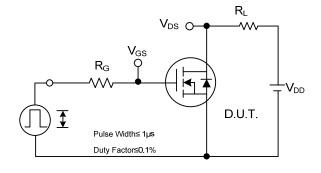
# Peak Diode Recovery dv/dt Test Circuit

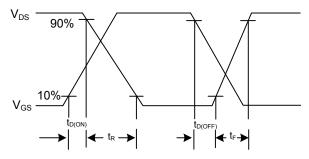


Peak Diode Recovery dv/dt Waveforms

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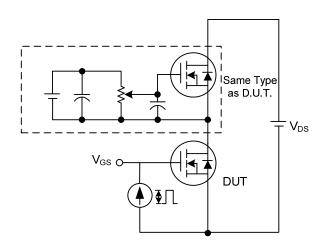
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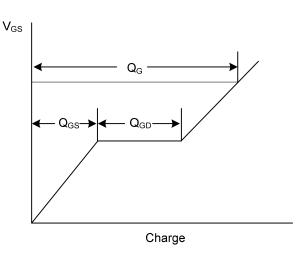




**Switching Test Circuit** 

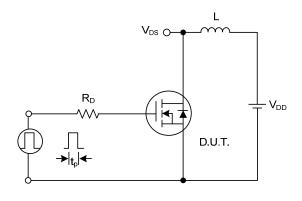
**Switching Waveforms** 

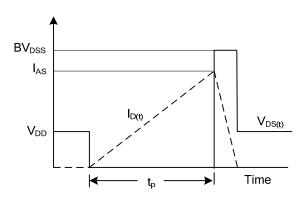




**Gate Charge Test Circuit** 

**Gate Charge Waveform** 





**Unclamped Inductive Switching Test Circuit** 

**Unclamped Inductive Switching Waveforms** 

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